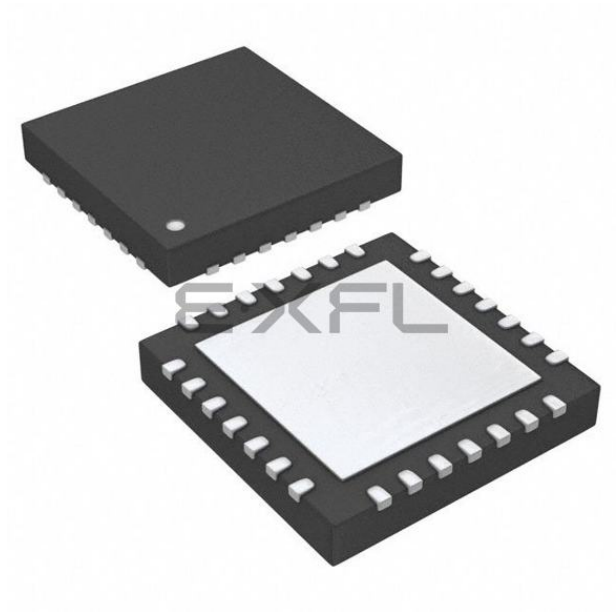
Microchip Technology - PIC24F16KA302-I/ML Datasheet



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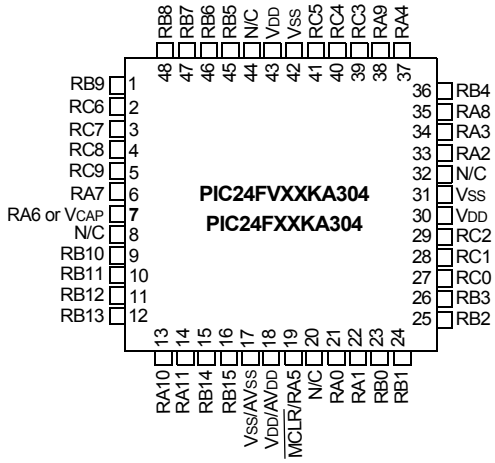
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16ka302-i-ml

Pin Diagrams

48-Pin UQFN(1,2,3)



Pin	Pin Features	
	PIC24FVXXKA304	PIC24FXXKA304
1	SDA1/T1CK/U1RTS/CTED4/CN21/RB9	SDA1/T1CK/U1RTS/CTED4/CN21/RB9
2	U1RX/CN18/RC6	U1RX/CN18/RC6
3	U1TX/CN17/RC7	U1TX/CN17/RC7
4	OC2/CN20/RC8	OC2/CN20/RC8
5	IC2/CTED7/CN19/RC9	IC2/CTED7/CN19/RC9
6	IC1/CTED3/CN9/RA7	IC1/CTED3/CN9/RA7
7	**VCAP**	**C20UT/OC1/CTED1/INT2CN8/RA6**
8	N/C	N/C
9	PGED2/SDI1/CTED11/CN16/RB10	PGED2/SDI1/CTED11/CN16/RB10
10	PGEC2/SCK1/CTED9/CN15/RB11	PGEC2/SCK1/CTED9/CN15/RB11
11	AN12/HLVDIN/CTED2/**INT2**/CN14/RB12	AN12/HLVDIN/CTED2/CN14/RB12
12	AN11/SDO1/CTPLS/CN13/RB13	AN11/SDO1/CTPLS/CN13/RB13
13	OC3/CN35/RA10	OC3/CN35/RA10
14	IC3/CTED8/CN36/RA11	IC3/CTED8/CN36/RA11
15	CVREF/AN10/C3INB/RTCC/C1OUT/OCFA/CTED5/INT1/CN12/RB14	CVREF/AN10/C3INB/RTCC/C1OUT/OCFA/CTED5/INT1/CN12/RB14
16	AN9/C3INA/T3CK/T2CK/REFO/SS1/CTED6/CN11/RB15	AN9/C3INA/T3CK/T2CK/REFO/SS1/CTED6/CN11/RB15
17	VSS/AVSS	VSS/AVSS
18	VDD/AVDD	VDD/AVDD
19	MCLR/RA5	MCLR/RA5
20	N/C	N/C
21	VREF+/CVREF+/AN0/C3INC/CTED1/CN2/RA0	VREF+/CVREF+/AN0/C3INC/CN2/RA0
22	CVREF-/VREF-/AN1/CN3/RA1	CVREF-/VREF-/AN1/CN3/RA1
23	PGED1/AN2/ULPWU/CTCMP/C1IND/C2INB/C3IND/U2TX/CN4/RB0	PGED1/AN2/ULPWU/CTCMP/C1IND/C2INB/C3IND/U2TX/CN4/RB0
24	PGEC1/AN3/C1INC/C2INA/U2RX/CTED12/CN5/RB1	PGEC1/AN3/C1INC/C2INA/U2RX/CTED12/CN5/RB1
25	AN4/C1INB/C2IND/SDA2/T5CK/T4CK/CTED13/CN6/RB2	AN4/C1INB/C2IND/SDA2/T5CK/T4CK/CTED13/CN6/RB2
26	AN5/C1INA/C2INC/SCL2/CN7/RB3	AN5/C1INA/C2INC/SCL2/CN7/RB3
27	AN6/CN32/RC0	AN6/CN32/RC0
28	AN7/CN31/RC1	AN7/CN31/RC1
29	AN8/CN10/RC2	AN8/CN10/RC2
30	VDD	VDD
31	VSS	VSS
32	N/C	N/C
33	OSCI/AN13/CLKI/CN30/RA2	OSCI/AN13/CLKI/CN30/RA2
34	OSCO/AN14/CLKO/CN29/RA3	OSCO/AN14/CLKO/CN29/RA3
35	OCFB/CN33/RA8	OCFB/CN33/RA8
36	SOSCI/AN15/U2RTS/CN1/RB4	SOSCI/AN15/U2RTS/CN1/RB4
37	SOSCO/SCLKI/U2CTS/CN0/RA4	SOSCO/SCLKI/U2CTS/CN0/RA4
38	SS2/CN34/RA9	SS2/CN34/RA9
39	SDI2/CN28/RC3	SDI2/CN28/RC3
40	SDO2/CN25/RC4	SDO2/CN25/RC4
41	SCK2/CN26/RC5	SCK2/CN26/RC5
42	VSS	VSS
43	VDD	VDD
44	N/C	N/C
45	PGED3/ASDA1(2)/CN27/RB5	PGED3/ASDA1(2)/CN27/RB5
46	PGEC3/ASCL1(2)/CN24/RB6	PGEC3/ASCL1(2)/CN24/RB6
47	C2OUT/OC1/INT0/CN23/RB7	INT0/CN23/RB7
48	SCL1/U1CTS/C3OUT/CTED10/CN22/RB8	SCL1/U1CTS/C3OUT/CTED10/CN22/RB8

Legend: Pin numbers in **bold** indicate pin function differences between PIC24FV and PIC24F devices.

Note 1: Exposed pad on underside of device is connected to VSS.

2: Alternative multiplexing for SDA1 (ASDA1) and SCL1 (ASCL1) when the I2CSEL Configuration bit is set.

3: PIC24F32KA3XX device pins have a maximum voltage of 3.6V and are not 5V tolerant.

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

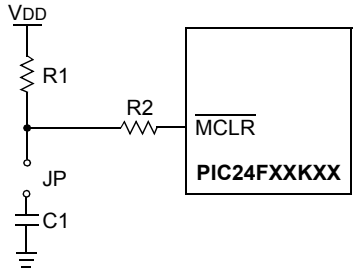
2.3 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides two specific device functions: Device Reset, and Device Programming and Debugging. If programming and debugging are not required in the end application, a direct connection to VDD may be all that is required. The addition of other components, to help increase the application's resistance to spurious Resets from voltage sags, may be beneficial. A typical configuration is shown in Figure 2-1. Other circuit designs may be implemented, depending on the application's requirements.

During programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R1 and C1 will need to be adjusted based on the application and PCB requirements. For example, it is recommended that the capacitor, C1, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations by using a jumper (Figure 2-2). The jumper is replaced for normal run-time operations.

Any components associated with the $\overline{\text{MCLR}}$ pin should be placed within 0.25 inch (6 mm) of the pin.

FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: R1 ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

2: R2 ≤ 470Ω will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor, C, in the event of $\overline{\text{MCLR}}$ pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

3.3.2 DIVIDER

The divide block supports 32-bit/16-bit and 16-bit/16-bit signed and unsigned integer divide operations with the following data sizes:

1. 32-bit signed/16-bit signed divide
2. 32-bit unsigned/16-bit unsigned divide
3. 16-bit signed/16-bit signed divide
4. 16-bit unsigned/16-bit unsigned divide

The quotient for all divide instructions ends up in W0 and the remainder in W1. Sixteen-bit signed and unsigned `DIV` instructions can specify any W register for both the 16-bit divisor (Wn), and any W register (aligned) pair (W(m + 1):Wm) for the 32-bit dividend. The divide algorithm takes one cycle per bit of divisor, so both 32-bit/16-bit and 16-bit/16-bit instructions take the same number of cycles to execute.

3.3.3 MULTI-BIT SHIFT SUPPORT

The PIC24F ALU supports both single bit and single-cycle, multi-bit arithmetic and logic shifts. Multi-bit shifts are implemented using a shifter block, capable of performing up to a 15-bit arithmetic right shift, or up to a 15-bit left shift, in a single cycle. All multi-bit shift instructions only support Register Direct Addressing for both the operand source and result destination.

A full summary of instructions that use the shift operation is provided in Table 3-2.

TABLE 3-2: INSTRUCTIONS THAT USE THE SINGLE AND MULTI-BIT SHIFT OPERATION

Instruction	Description
`ASR`	Arithmetic shift right source register by one or more bits.
`SL`	Shift left source register by one or more bits.
`LSR`	Logical shift right source register by one or more bits.

NOTES:

EXAMPLE 5-2: ERASING A PROGRAM MEMORY ROW – 'C' LANGUAGE CODE

```
// C example using MPLAB C30

    int __attribute__ ((space(auto_psv))) progAddr = 0x1234;// Global variable located in Pgm Memory
    unsigned int offset;

//Set up pointer to the first memory location to be written

    TBLPAG = __builtin_tblpage(&progAddr);              // Initialize PM Page Boundary SFR
    offset = __builtin_tbloffset(&progAddr);            // Initialize lower word of address

    __builtin_tblwtl(offset, 0x0000);                   // Set base address of erase block
                                                        // with dummy latch write

    NVMCON = 0x4058;                                    // Initialize NVMCON

    asm("DISI #5");                                     // Block all interrupts for next 5
                                                        // instructions
    __builtin_write_NVM();                              // C30 function to perform unlock
                                                        // sequence and set WR
```

EXAMPLE 5-3: LOADING THE WRITE BUFFERS – ASSEMBLY LANGUAGE CODE

```
; Set up NVMCON for row programming operations
       MOV     #0x4004, W0                  ;
       MOV     W0, NVMCON                   ; Initialize NVMCON
; Set up a pointer to the first program memory location to be written
; program memory selected, and writes enabled
       MOV     #0x0000, W0                  ;
       MOV     W0, TBLPAG                   ; Initialize PM Page Boundary SFR
       MOV     #0x6000, W0                  ; An example program memory address
; Perform the TBLWT instructions to write the latches
; 0th_program_word
       MOV     #LOW_WORD_0, W2              ;
       MOV     #HIGH_BYTE_0, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
; 1st_program_word
       MOV     #LOW_WORD_1, W2              ;
       MOV     #HIGH_BYTE_1, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
;  2nd_program_word
       MOV     #LOW_WORD_2, W2              ;
       MOV     #HIGH_BYTE_2, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
       •
       •
       •
; 32nd_program_word
       MOV     #LOW_WORD_31, W2             ;
       MOV     #HIGH_BYTE_31, W3            ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0]                     ; Write PM high byte into program latch
```

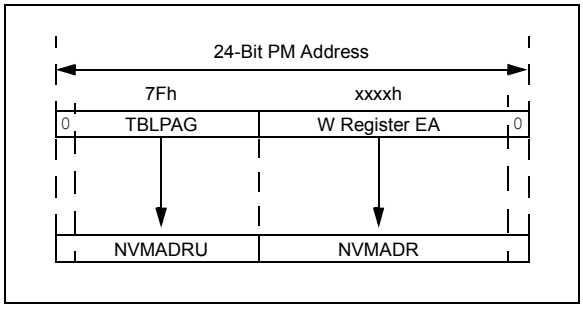
6.3 NVM Address Register

As with Flash program memory, the NVM Address registers, NVMADRU and NVMADR, form the 24-bit Effective Address (EA) of the selected row or word for data EEPROM operations. The NVMADRU register is used to hold the upper 8 bits of the EA, while the NVMADR register is used to hold the lower 16 bits of the EA. These registers are not mapped into the Special Function Register (SFR) space. Instead, they directly capture the EA<23:0> of the last table write instruction that has been executed and selects the data EEPROM row to erase. Figure 6-1 depicts the program memory EA that is formed for programming and erase operations.

Like program memory operations, the Least Significant bit (LSb) of NVMADR is restricted to even addresses. This is because any given address in the data EEPROM space consists of only the lower word of the program memory width; the upper word, including the uppermost "phantom byte", are unavailable. This means that the LSb of a data EEPROM address will always be '0'.

Similarly, the Most Significant bit (MSb) of NVMADRU is always '0', since all addresses lie in the user program space.

FIGURE 6-1: DATA EEPROM ADDRESSING WITH TBLPAG AND NVM ADDRESS REGISTERS



6.4 Data EEPROM Operations

The EEPROM block is accessed using table read and write operations similar to those used for program memory. The TBLWTH and TBLRDH instructions are not required for data EEPROM operations since the memory is only 16 bits wide (data on the lower address is valid only). The following programming operations can be performed on the data EEPROM:

- Erase one, four or eight words
- Bulk erase the entire data EEPROM
- Write one word
- Read one word

Note 1: Unexpected results will be obtained if the user attempts to read the EEPROM while a programming or erase operation is underway.

2: The C30 C compiler includes library procedures to automatically perform the table read and table write operations, manage the Table Pointer and write buffers, and unlock and initiate memory write sequences. This eliminates the need to create assembler macros or time critical routines in C for each application.

The library procedures are used in the code examples detailed in the following sections. General descriptions of each process are provided for users who are not using the C30 compiler libraries.

REGISTER 8-2: CORCON: CPU CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/C-0, HSC	R/W-0	U-0	U-0
—	—	—	—	IPL3(2)	PSV(1)	—	—
bit 7							bit 0

Legend:	C = Clearable bit	HSC = Hardware Settable/Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as '0'

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit(2)
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

bit 1-0 **Unimplemented:** Read as '0'

Note 1: See Register 3-2 for the description of this bit, which is not dedicated to interrupt control functions.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

Note: Bit 2 is described in **Section 3.0 "CPU"**.

REGISTER 8-23: IPC6: INTERRUPT PRIORITY CONTROL REGISTER 6

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	T4IP2	T4IP1	T4IP0	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	OC3IP2	OC3IP1	OC3IP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **T4IP<2:0>:** Timer4 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11-7 **Unimplemented:** Read as '0'

bit 6-4 **OC3IP<2:0>:** Output Compare Channel 3 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as '0'

REGISTER 8-30: IPC18: INTERRUPT PRIORITY CONTROL REGISTER 18

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	HLVDIP2	HLVDIP1	HLVDIP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as '0'

bit 2-0 **HLVDIP<2:0>:** High/Low-Voltage Detect Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 8-31: IPC19: INTERRUPT PRIORITY CONTROL REGISTER 19

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	CTMUIP2	CTMUIP1	CTMUIP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-4 **CTMUIP<2:0>:** CTMU Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as '0'

REGISTER 10-2: DSWAKE: DEEP SLEEP WAKE-UP SOURCE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS
—	—	—	—	—	—	—	DSINT0
bit 15							bit 8

R/W-0, HS	U-0	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	U-0	R/W-0, HS
DSFLT	—	—	DSWDT	DSRTCC	DSMCLR	—	DSPOR(2,3)
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **DSINT0:** Deep Sleep Interrupt-on-Change bit
1 = Interrupt-on-change was asserted during Deep Sleep
0 = Interrupt-on-change was not asserted during Deep Sleep

bit 7 **DSFLT:** Deep Sleep Fault Detect bit
1 = A Fault occurred during Deep Sleep and some Deep Sleep configuration settings may have been corrupted
0 = No Fault was detected during Deep Sleep

bit 6-5 **Unimplemented:** Read as '0'

bit 4 **DSWDT:** Deep Sleep Watchdog Timer Time-out bit
1 = The Deep Sleep Watchdog Timer timed out during Deep Sleep
0 = The Deep Sleep Watchdog Timer did not time out during Deep Sleep

bit 3 **DSRTCC:** Deep Sleep Real-Time Clock and Calendar (RTCC) Alarm bit
1 = The Real-Time Clock and Calendar triggered an alarm during Deep Sleep
0 = The Real-Time Clock and Calendar did not trigger an alarm during Deep Sleep

bit 2 **DSMCLR:** Deep Sleep $\overline{\text{MCLR}}$ Event bit
1 = The $\overline{\text{MCLR}}$ pin was active and was asserted during Deep Sleep
0 = The $\overline{\text{MCLR}}$ pin was not active, or was active, but not asserted during Deep Sleep

bit 1 **Unimplemented:** Read as '0'

bit 0 **DSPOR:** Deep Sleep Power-on Reset Event bit(2,3)
1 = The VDD supply POR circuit was active and a POR event was detected
0 = The VDD supply POR circuit was not active, or was active, but did not detect a POR event

Note 1: All register bits are cleared when the DSEN (DSCON<15>) bit is set.

2: All register bits are reset only in the case of a POR event outside of Deep Sleep mode, except bit, DSPOR, which does not reset on a POR event that is caused due to a Deep Sleep exit.

3: Unlike the other bits in this register, this bit can be set outside of Deep Sleep.

10.3 Ultra Low-Power Wake-up

The Ultra Low-Power Wake-up (ULPWU) on pin, RB0, allows a slow falling voltage to generate an interrupt without excess current consumption.

To use this feature:

1. Charge the capacitor on RB0 by configuring the RB0 pin to an output and setting it to '1'.
2. Stop charging the capacitor by configuring RB0 as an input.
3. Discharge the capacitor by setting the ULPEN and ULPSINK bits in the ULPWCON register.
4. Configure Sleep mode.
5. Enter Sleep mode.

When the voltage on RB0 drops below VIL, the device wakes up and executes the next instruction.

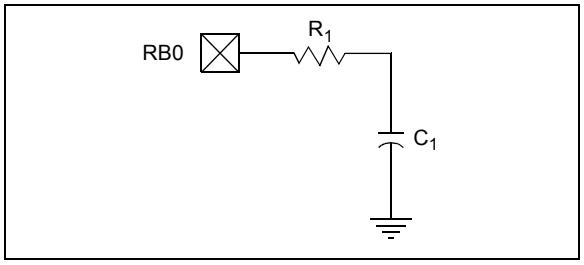
This feature provides a low-power technique for periodically waking up the device from Sleep mode.

The time-out is dependent on the discharge time of the RC circuit on RB0.

When the ULPWU module wakes the device from Sleep mode, the ULPWUIF bit (IFS5<0>) is set. Software can check this bit upon wake-up to determine the wake-up source. See Example 10-3 for initializing the ULPWU module.

A series resistor, between RB0 and the external capacitor, provides overcurrent protection for the RB0/AN0/ULPWU pin and enables software calibration of the time-out (see Figure 10-1).

FIGURE 10-1: SERIES RESISTOR



A timer can be used to measure the charge time and discharge time of the capacitor. The charge time can then be adjusted to provide the desired delay in Sleep. This technique compensates for the affects of temperature, voltage and component accuracy. The peripheral can also be configured as a simple, programmable Low-Voltage Detect (LVD) or temperature sensor.

EXAMPLE 10-3: ULTRA LOW-POWER WAKE-UP INITIALIZATION

```
//******************************
// 1. Charge the capacitor on RB0
//******************************
    TRISBbits.TRISB0 = 0;
    LATBbits.LATB0 = 1;
    for(i = 0; i < 10000; i++) Nop();
//******************************
//2. Stop Charging the capacitor
//   on RB0
//******************************
    TRISBbits.TRISB0 = 1;
//******************************
//3. Enable ULPWU Interrupt
//******************************
IFS5bits.ULPWUIF = 0;
IEC5bits.ULPWUIE = 1;
IPC21bits.ULPWUIP = 0x7;
//******************************
//4. Enable the Ultra Low Power
//   Wakeup module and allow
//   capacitor discharge
//******************************
    ULPWCONbits.ULPEN = 1;
    ULPWCONbit.ULPSINK = 1;
//******************************
//5. Enter Sleep Mode
//******************************
    Sleep();
//for sleep, execution will
//resume here
```

EQUATION 16-1: RELATIONSHIP BETWEEN DEVICE AND SPIx CLOCK SPEED(1)

$$FSCK = \frac{FCY}{\text{Primary Prescaler} * \text{Secondary Prescaler}}$$

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

TABLE 16-1: SAMPLE SCKx FREQUENCIES(1,2)

FCY = 16 MHz		Secondary Prescaler Settings				
		1:1	2:1	4:1	6:1	8:1
Primary Prescaler Settings	1:1	Invalid	8000	4000	2667	2000
	4:1	4000	2000	1000	667	500
	16:1	1000	500	250	167	125
	64:1	250	125	63	42	31
FCY = 5 MHz						
Primary Prescaler Settings	1:1	5000	2500	1250	833	625
	4:1	1250	625	313	208	156
	16:1	313	156	78	52	39
	64:1	78	39	20	13	10

Note 1: Based on FCY = FOSC/2; Doze mode and PLL are disabled.

2: SCKx frequencies are indicated in kHz.

REGISTER 22-1: AD1CON1: A/D CONTROL REGISTER 1

R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	—	—	MODE12	FORM1	FORM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0, HSC	R/C-0, HSC
SSRC3	SSRC2	SSRC1	SSRC0	—	ASAM	SAMP	DONE
bit 7							bit 0

Legend:	C = Clearable bit	U = Unimplemented bit, read as '0'	
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** A/D Operating Mode bit
1 = A/D Converter module is operating
0 = A/D Converter is off

bit 14 **Unimplemented:** Read as '0'

bit 13 **ADSIDL:** A/D Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **MODE12:** 12-Bit Operation Mode bit
1 = 12-bit A/D operation
0 = 10-bit A/D operation

bit 9-8 **FORM<1:0>:** Data Output Format bits (see the following formats)
11 = Fractional result, signed, left-justified
10 = Absolute fractional result, unsigned, left-justified
01 = Decimal result, signed, right-justified
00 = Absolute decimal result, unsigned, right-justified

bit 7-4 **SSRC<3:0>:** Sample Clock Source Select bits
1111 = Not available; do not use
•
•
•
1000 = Not available; do not use
0111 = Internal counter ends sampling and starts conversion (auto-convert)
0110 = Not available; do not use
0101 = Timer1 event ends sampling and starts conversion
0100 = CTMU event ends sampling and starts conversion
0011 = Timer5 event ends sampling and starts conversion
0010 = Timer3 event ends sampling and starts conversion
0001 = INT0 event ends sampling and starts conversion
0000 = Clearing the SAMP bit in software ends sampling and begins conversion

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** A/D Sample Auto-Start bit
1 = Sampling begins immediately after the last conversion; SAMP bit is auto-set
0 = Sampling begins when the SAMP bit is manually set

bit 1 **SAMP:** A/D Sample Enable bit
1 = A/D Sample-and-Hold amplifiers are sampling
0 = A/D Sample-and-Hold amplifiers are holding

bit 0 **DONE:** A/D Conversion Status bit
1 = A/D conversion cycle has completed
0 = A/D conversion cycle has not started or is in progress

REGISTER 22-5: AD1CHS: A/D SAMPLE SELECT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB2	CH0NB1	CH0NB0	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA2	CH0NA1	CH0NA0	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **CH0NB<2:0>:** Sample B Channel 0 Negative Input Select bits
111 = AN6(1)
110 = AN5(2)
101 = AN4
100 = AN3
011 = AN2
010 = AN1
001 = AN0
000 = AVSS

bit 12-8 **CH0SB<4:0>:** S/H Amplifier Positive Input Select for MUX B Multiplexer Setting bits
11111 = Unimplemented, do not use
11110 = AVDD
11101 = AVSS
11100 = Upper guardband rail (0.785 * VDD)
11011 = Lower guardband rail (0.215 * VDD)
11010 = Internal Band Gap Reference (VBG)(3)
11001-10010 = Unimplemented, do not use
10001 = No channels are connected, all inputs are floating (used for CTMU)
10000 = No channels are connected, all inputs are floating (used for CTMU temperature sensor input)
01111 = AN15
01110 = AN14
01101 = AN13
01100 = AN12
01011 = AN11
01010 = AN10
01001 = AN9
01000 = AN8(1)
00111 = AN7(1)
00110 = AN6(1)
00101 = AN5(2)
00100 = AN4
00011 = AN3
00010 = AN2
00001 = AN1
00000 = AN0

bit 7-5 **CH0NA<2:0>:** Sample A Channel 0 Negative Input Select bits
The same definitions as for CHONB<2:0>.

bit 4-0 **CH0SA<4:0>:** Sample A Channel 0 Positive Input Select bits
The same definitions as for CHONA<4:0>.

Note 1: This is implemented on 44-pin devices only.
2: This is implemented on 28-pin and 44-pin devices only.
3: The band gap value used for this input is 2x or 4x the internal VBG, which is selected when PVCFG<1:0> = 1x.

REGISTER 22-10: AD1CTMUENH: A/D CTMU ENABLE REGISTER (HIGH WORD)(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	CTMEN17	CTMEN16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-2 **Unimplemented:** Read as '0'.

bit 1-0 **CTMEN<17:16>:** CTMU Enabled During Conversion bits

1 = CTMU is enabled and connected to the selected channel during conversion
0 = CTMU is not connected to this channel

Note 1: Unimplemented channels are read as '0'.

REGISTER 22-11: AD1CTMUENL: A/D CTMU ENABLE REGISTER (LOW WORD)(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMEN15	CTMEN14	CTMEN13	CTMEN12	CTMUEN11	CTMEN10	CTMEN9	CTMEN8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMEN7	CTMEN6	CTMEN5	CTMEN4	CTMEN3	CTMEN2	CTMEN1	CTMEN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **CTMEN<15:0>:** CTMU Enabled During Conversion bits

1 = CTMU is enabled and connected to the selected channel during conversion
0 = CTMU is not connected to this channel

Note 1: Unimplemented channels are read as '0'.

24.0 COMPARATOR VOLTAGE REFERENCE

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Comparator Voltage Reference, refer to the *"PIC24F Family Reference Manual"*, **Section 20. "Comparator Module Voltage Reference Module"** (DS39709).

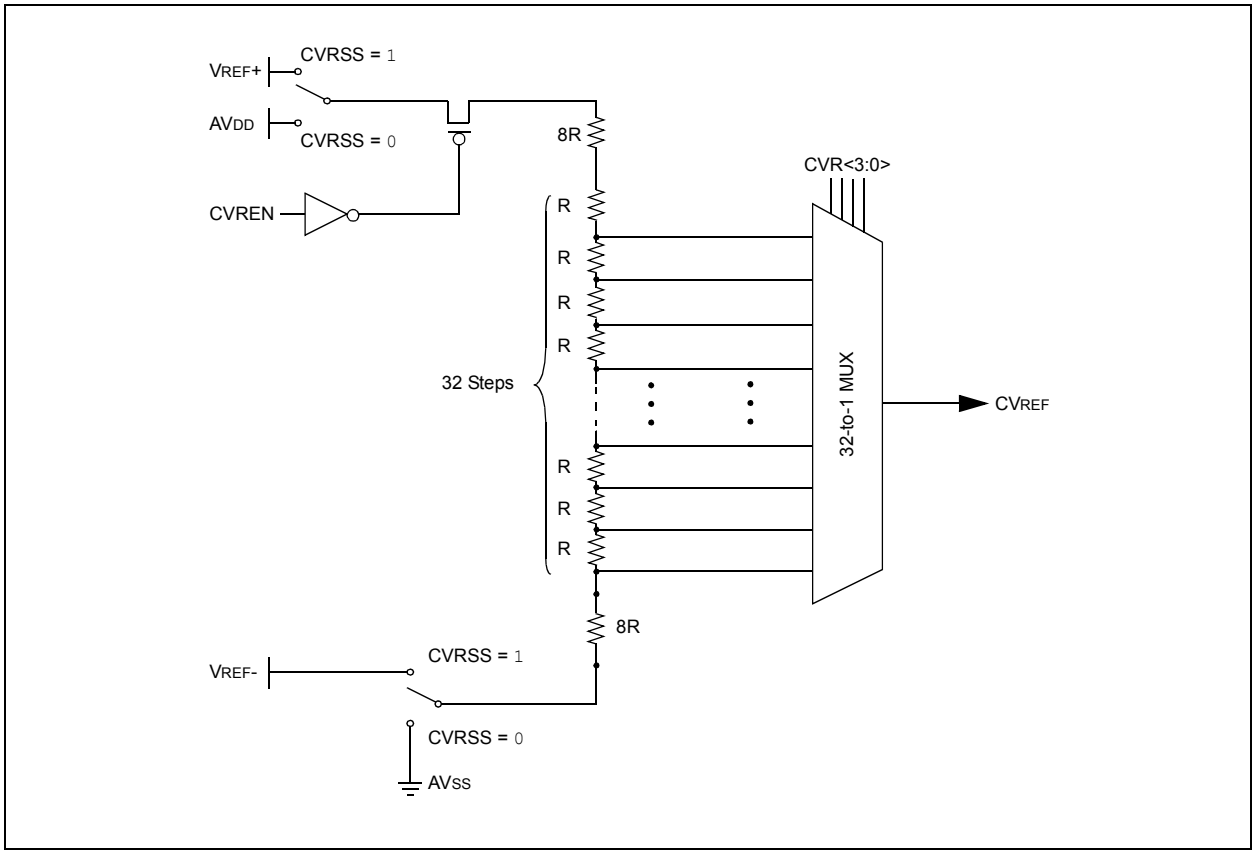
24.1 Configuring the Comparator Voltage Reference

The comparator voltage reference module is controlled through the CVRCON register (Register 24-1). The comparator voltage reference provides a range of output voltages, with 32 distinct levels.

The comparator voltage reference supply voltage can come from either VDD and VSS or the external VREF+ and VREF-. The voltage source is selected by the CVRSS bit (CVRCON<5>).

The settling time of the comparator voltage reference must be considered when changing the CVREF output.

FIGURE 24-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



27.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

27.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

27.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

27.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

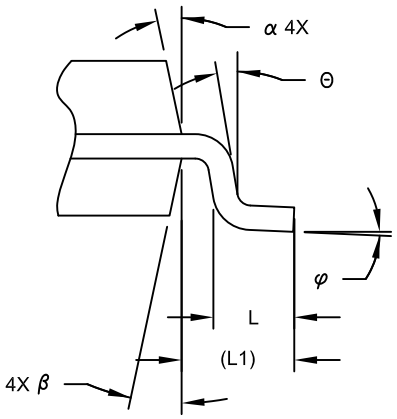
The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

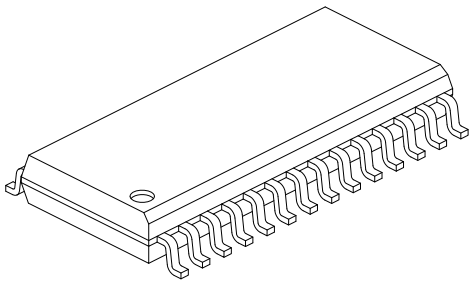
NOTES:

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

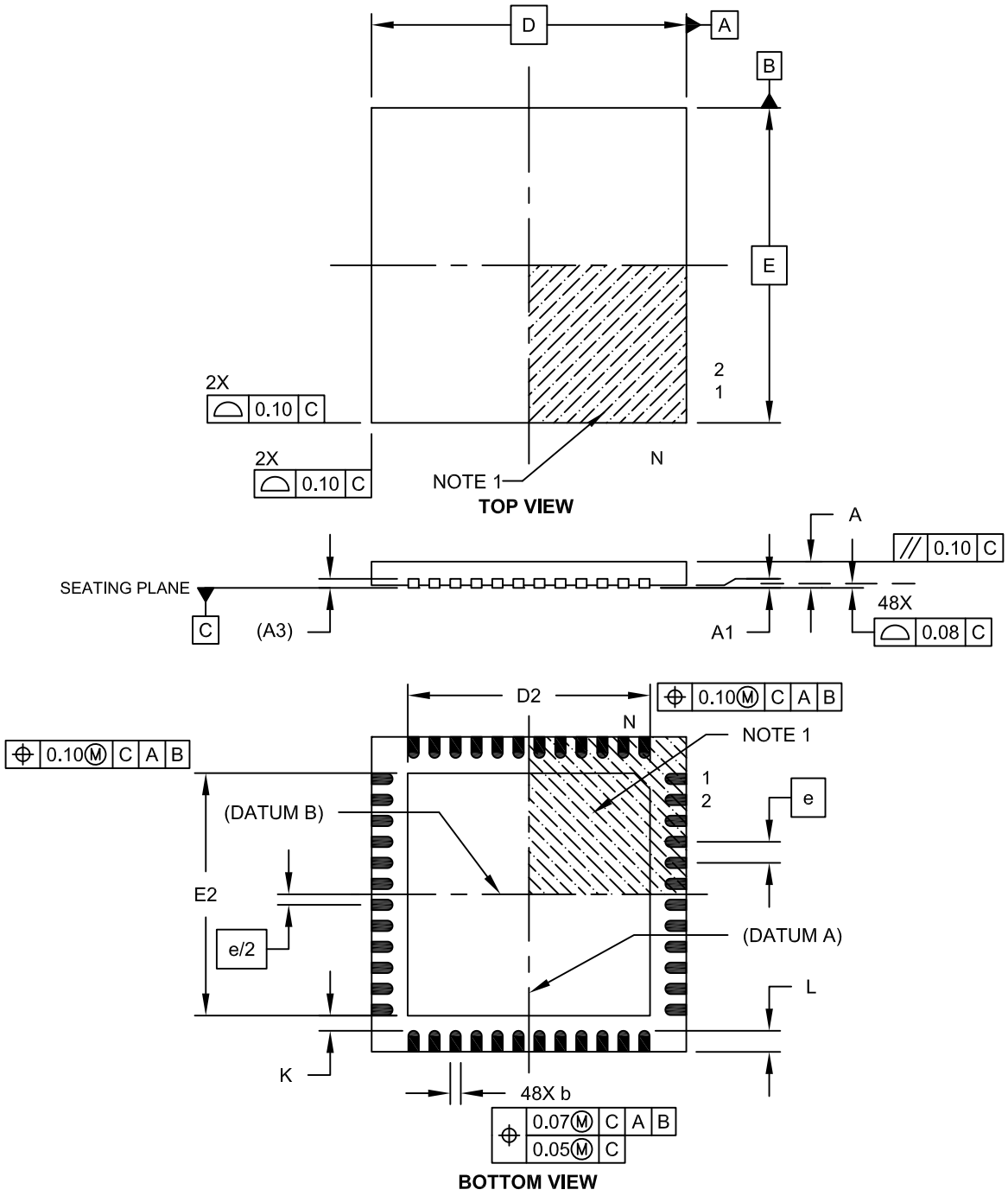
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-153A Sheet 1 of 2